

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A spin coating method, comprising:  
applying a material to a substrate;  
spinning the substrate and the material at a substantially constant first speed;  
following the spinning, decreasing a rate of spinning to a substantially constant second speed;  
and  
following decreasing, gradually increasing a rate of the spinning to a substantially constant third speed that is greater than the first speed.
2. (Previously Presented) The method of claim 1, wherein spinning the substrate and the material at the first speed comprises substantially filling recesses formed in the substrate with the material.
3. (Previously Presented) The method of claim 1, wherein decreasing the rate of spinning to the second speed comprises permitting material located within recesses formed in the substrate to set.
4. (Previously Presented) The method of claim 1, further comprising:  
spinning the substrate and the material at the third speed to form a layer comprising the material over a surface of the substrate to a desired thickness.
- 5-6. (Canceled)
7. (Currently amended) A spin coating method, comprising:  
applying a material to a substrate;

spinning the substrate and the material at a first speed that permits the material to flow into recesses formed in the substrate;  
spinning the substrate at a second speed that permits the material within the recesses to set; and  
following spinning the substrate at the second speed, gradually increasing a rate of spinning of the substrate to a third speed that is greater than the first speed.

8. (Previously Presented) The method of claim 7, wherein spinning the substrate at the second speed follows spinning the substrate at the first speed.

9. (Previously Presented) The method of claim 8, wherein spinning the substrate at the second speed comprises decreasing a rate at which the substrate is spun.

10. (Previously Presented) The method of claim 7, wherein spinning the substrate and the material at the first speed comprises substantially filling the recesses with the material.

11. (Previously Presented) The method of claim 7, further comprising:  
spinning the substrate and the material at the third speed comprises to form a layer comprising the material over a surface of the substrate to a desired thickness.

12-13. (Canceled)

14. (Currently amended) A spin coating method, comprising:  
applying a material to a substrate;  
spinning the substrate at a first speed to at least partially spread the material;  
following spinning the substrate at the first speed, spinning the substrate at a second speed to permit at least some of the material to flow into at least one recess formed in the substrate; and  
following spinning the substrate at the second speed, gradually increasing a rate of spinning of the substrate to a third speed that is greater than the first speed.

15. (Previously Presented) The method of claim 14, wherein spinning the substrate at the first speed comprises substantially filling the at least one recess with the material.

16. (Previously Presented) The method of claim 14, wherein spinning the substrate at the second speed comprises spinning the substrate at a speed that is slower than the first speed.

17-19. (Canceled)

20. (Previously Presented) The method of claim 14, further comprising:  
spinning the substrate at the third speed to form a layer comprising the material over a surface of the substrate to a desired thickness.

21. (Previously Presented) The method of claim 1, further comprising:  
following gradually increasing, again decreasing a rate of spinning of the substrate to a fourth speed.

22. (Previously Presented) The method of claim 21, comprising permitting the material to set further while spinning the substrate at the fourth speed.

23. (Previously Presented) The method of claim 21, further comprising:  
following the again decreasing, again increasing a rate of spinning of the substrate to a fifth speed.

24. (Previously Presented) The method of claim 23, comprising substantially removing solvent from the material while spinning the substrate at the fifth speed.

25. (Previously Presented) The method of claim 7, further comprising:

following gradually increasing, again decreasing a rate of spinning of the substrate to a fourth speed.

26. (Previously Presented) The method of claim 25, comprising permitting the material to set further while spinning the substrate at the fourth speed.

27. (Previously Presented) The method of claim 25, further comprising:  
following the again decreasing, again increasing a rate of spinning of the substrate to a fifth speed.

28. (Previously Presented) The method of claim 27, comprising substantially removing solvent from the material while spinning the substrate at the fifth speed.

29. (Previously Presented) The method of claim 14, further comprising:  
following gradually increasing, again decreasing a rate of spinning of the substrate to a fourth speed.

30. (Previously Presented) The method of claim 29, comprising permitting the material to set further while spinning the substrate at the fourth speed.

31. (Previously Presented) The method of claim 29, further comprising:  
following again decreasing, again increasing a rate of spinning of the substrate to a fifth speed.

32. (Previously Presented) The method of claim 31, comprising substantially removing solvent from the material while spinning the substrate at the fifth speed.